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TITLE: Method and apparatus for selective removal of material from wafer
alignment marks

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RELATED-US-APPL-DATA:

Application 10/154582 is a continuation-of US application 09/567631, filed May 9, 2000, PENDING
Application 09/567631 is a division-of US application 08/916997, filed August 20, 1997, US Patent No. 6103636

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REPRESENTATIVE-FIGURES: 2

ABSTRACT:

A process and apparatus for locally removing any material, such as a refractory metal, in particular tungsten, from any desired area of a wafer, such as an alignment mark area of a silicon wafer in process during the formation of integrated circuits thereon.

CROSS REFERENCE TO RELATED APPLICATIONS

[0001] This application is a continuation of application Ser. No. 09/567,631, filed May 9, 2000, pending, which is a divisional of application Ser. No. 08/916,997, filed Aug. 20, 1997, now U.S. Pat. No. 6,103,636, issued Aug. 15, 2000.